

**AMENDMENTS TO THE SPECIFICATION**

*Please replace paragraphs [0085] with the following amended paragraph:*

[0085] The buffer layer 311 is formed at an area, which is to be described later, such that the sealing layer 350 upper substrate 316 overlaps with the upper substrate 316 the sealing layer 350 and the buffer layer 311, as shown in FIG. ~~[[12]]~~12B, by spreading a buffer layer material on the upper substrate 316 where the sustain electrode pair 304Y, 304Z have been formed, as shown in FIG. 12A. Then, the upper dielectric layer 312 is formed by spreading a dielectric layer material on the upper substrate 316 except for an area where the buffer layer 311 has been formed. The sealing layer 350 is formed on the upper substrate 316 at areas other than where the upper dielectric layer 312 has been formed, as shown in FIG. 12B. The sealing layer 350 is formed by spreading a paste in use of screen printing or dispenser, wherein the paste is formed by mixing glass powder, solvent and binder together.